

Layer	Name	Material	Thickness	Constant	Board Layer Stack
	Top Overlay				
	Top Solder	SM-001	0.025mm	4	
1	Top Layer	CF-004	0.018mm		
	Dielectric-1	PP-006	0.220mm	4.1	
2	GND-1	CF-004	0.035mm		
	Core-1	Core-035	0.350mm	4.7	
3	INT-SIG-1	CF-004	0.035mm		
	Dielectric-2	PP-006	0.220mm	4.1	
4	INT-SIG-2	CF-004	0.035mm		
	Core-2	Core-035	0.350mm	4.7	
5	GND-2	CF-004	0.035mm		
	Dielectric-3	PP-006	0.220mm	4.1	
6	Bottom Layer	CF-004	0.018mm		
	Bottom Solder	SM-001	0.025mm	4	
	Bottom Overlay				

Total board thickness: 1.586mm

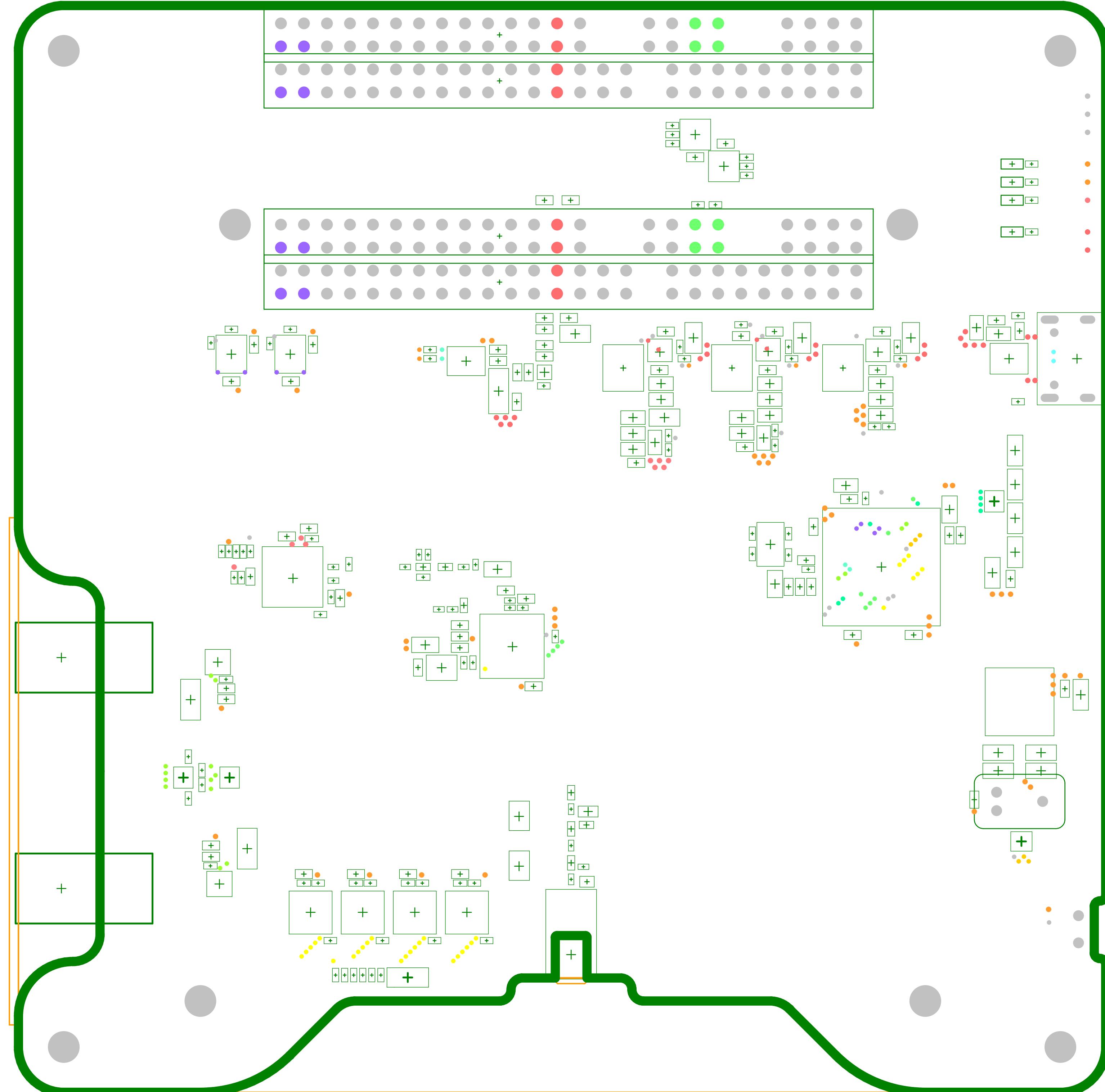
Pluton UPV	
Project: Estigia LoRa Comms PL - mPCIe SoM	
Layer: <a href="#">Board Shape</a> <a href="#">Component Guard</a>	<a href="#">Component Guard</a> <a href="#">Dimension</a>
Engineer: Juan Del Pino Mena	
Date: 2024-09-03	Revision: 0.3
	Size: A4

A

B

C

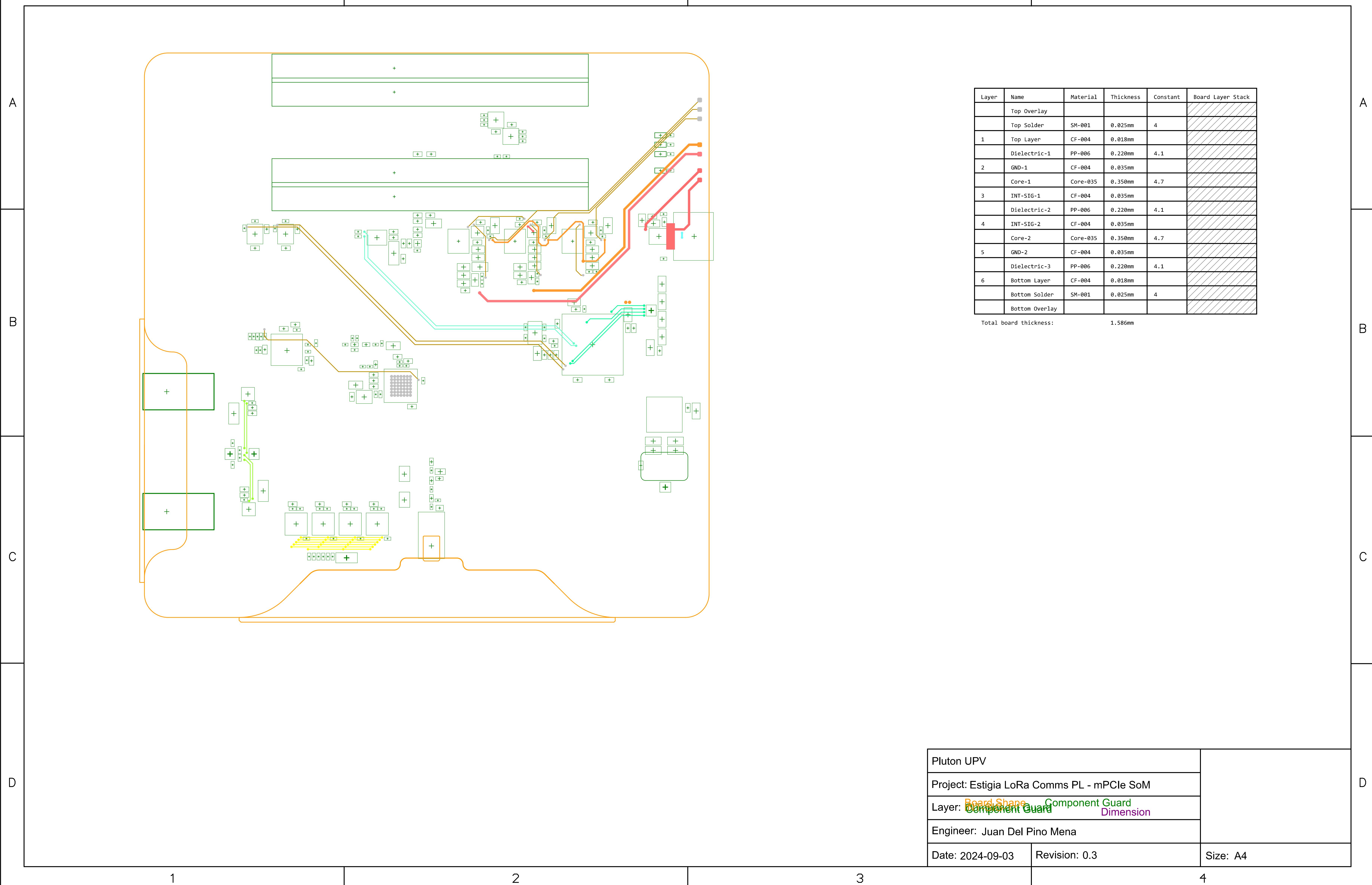
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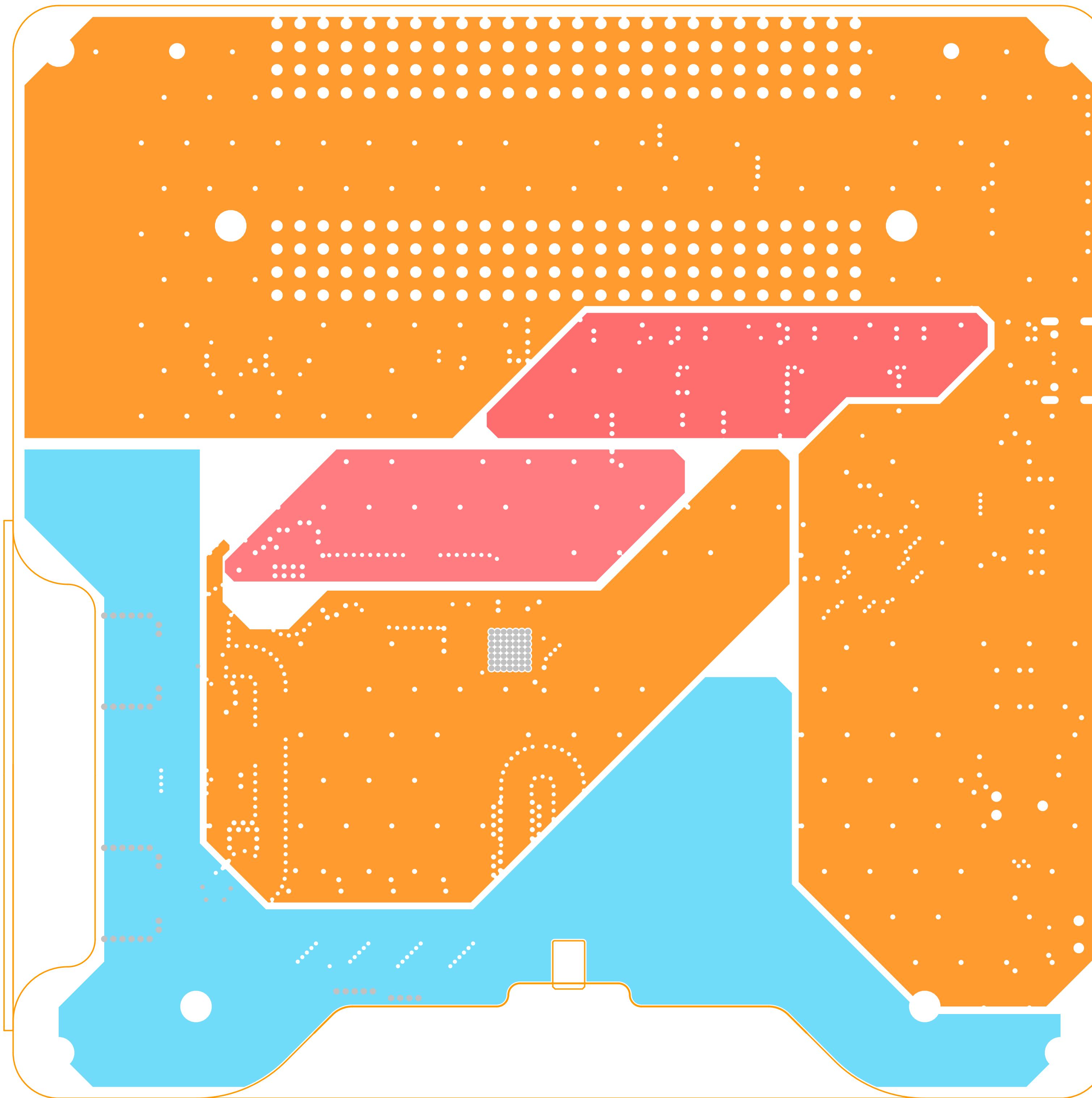


Layer	Name	Material	Thickness	Constant	Board Layer Stack
	Top Overlay				
	Top Solder	SM-001	0.025mm	4	
1	Top Layer	CF-004	0.018mm		
	Dielectric-1	PP-006	0.220mm	4.1	
2	GND-1	CF-004	0.035mm		
	Core-1	Core-035	0.350mm	4.7	
3	INT-SIG-1	CF-004	0.035mm		
	Dielectric-2	PP-006	0.220mm	4.1	
4	INT-SIG-2	CF-004	0.035mm		
	Core-2	Core-035	0.350mm	4.7	
5	GND-2	CF-004	0.035mm		
	Dielectric-3	PP-006	0.220mm	4.1	
6	Bottom Layer	CF-004	0.018mm		
	Bottom Solder	SM-001	0.025mm	4	
	Bottom Overlay				

Total board thickness: 1.586mm

Pluton UPV	
Project: Estigia LoRa Comms PL - mPCIe SoM	
Layer: <span style="color: orange;">Board Shape</span> <span style="color: green;">Component Guard</span> <span style="color: purple;">Dimension</span>	
Engineer: Juan Del Pino Mena	
Date: 2024-09-03	Revision: 0.3
	Size: A4

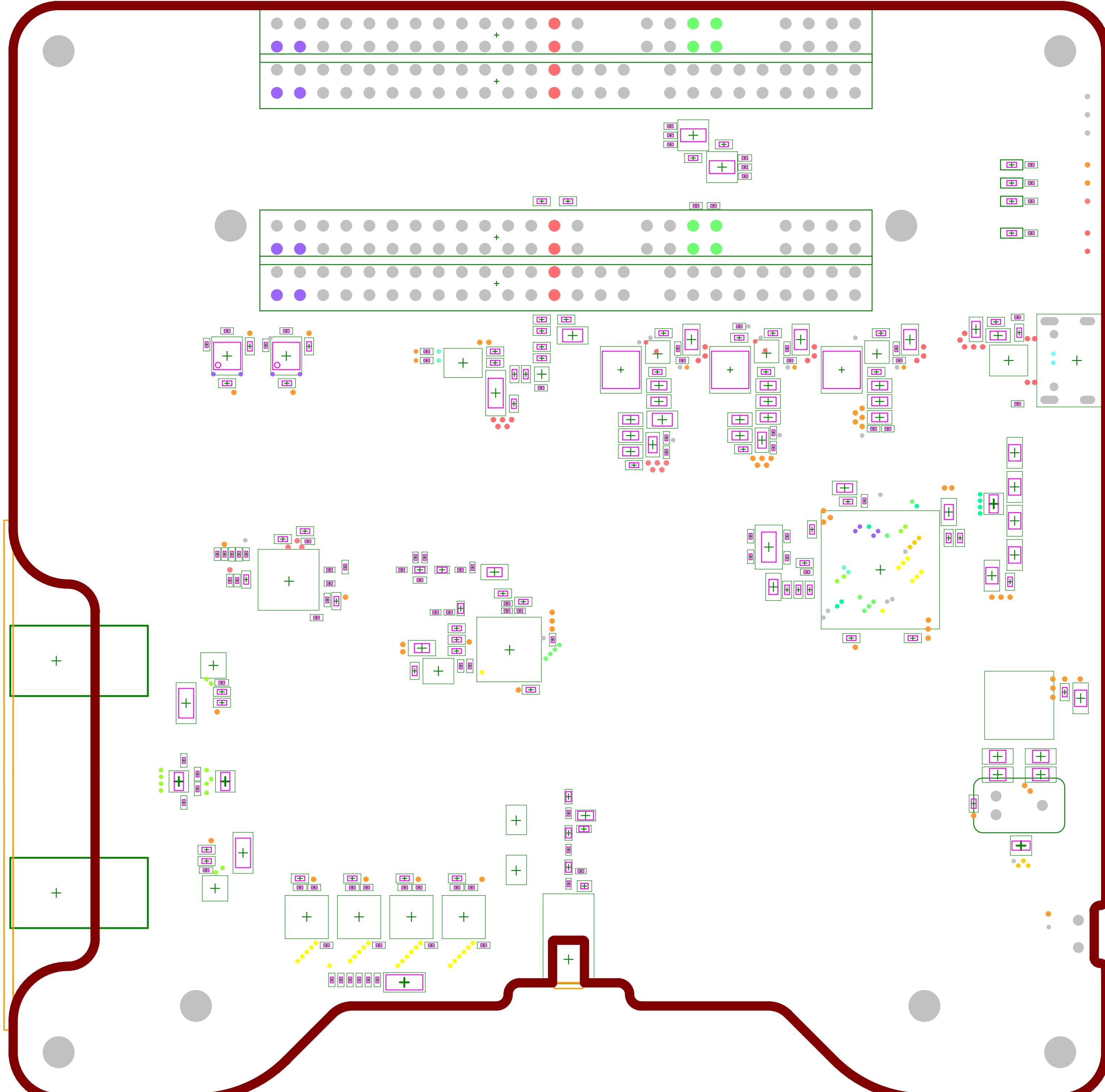




Layer	Name	Material	Thickness	Constant	Board Layer Stack
	Top Overlay				
	Top Solder	SM-001	0.025mm	4	
1	Top Layer	CF-004	0.018mm		
	Dielectric-1	PP-006	0.220mm	4.1	
2	GND-1	CF-004	0.035mm		
	Core-1	Core-035	0.350mm	4.7	
3	INT-SIG-1	CF-004	0.035mm		
	Dielectric-2	PP-006	0.220mm	4.1	
4	INT-SIG-2	CF-004	0.035mm		
	Core-2	Core-035	0.350mm	4.7	
5	GND-2	CF-004	0.035mm		
	Dielectric-3	PP-006	0.220mm	4.1	
6	Bottom Layer	CF-004	0.018mm		
	Bottom Solder	SM-001	0.025mm	4	
	Bottom Overlay				

Total board thickness: 1.586mm

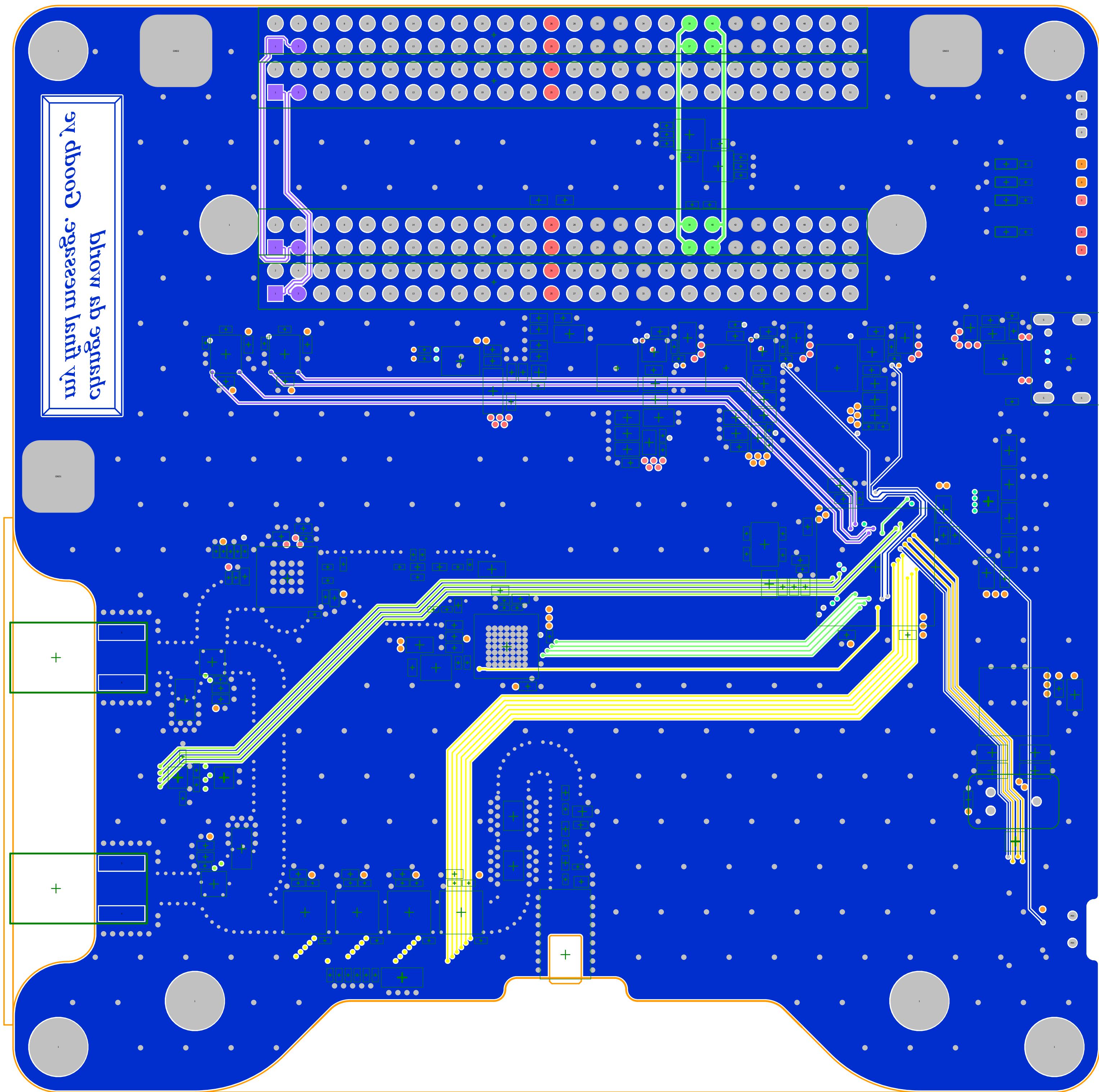
Pluton UPV	
Project: Estigia LoRa Comms PL - mPCIe SoM	
Layer: INT-SIG-2	Dimension
Engineer: Juan Del Pino Mena	
Date: 2024-09-03	Revision: 0.3
	Size: A4



Layer	Name	Material	Thickness	Constant	Board Layer Stack
	Top Overlay				
	Top Solder	SM-001	0.025mm	4	
1	Top Layer	CF-004	0.018mm		
	Dielectric-1	PP-006	0.220mm	4.1	
2	GND-1	CF-004	0.035mm		
	Core-1	Core-035	0.350mm	4.7	
3	INT-SIG-1	CF-004	0.035mm		
	Dielectric-2	PP-006	0.220mm	4.1	
4	INT-SIG-2	CF-004	0.035mm		
	Core-2	Core-035	0.350mm	4.7	
5	GND-2	CF-004	0.035mm		
	Dielectric-3	PP-006	0.220mm	4.1	
6	Bottom Layer	CF-004	0.018mm		
	Bottom Solder	SM-001	0.025mm	4	
	Bottom Overlay				

Total board thickness: 1.586mm

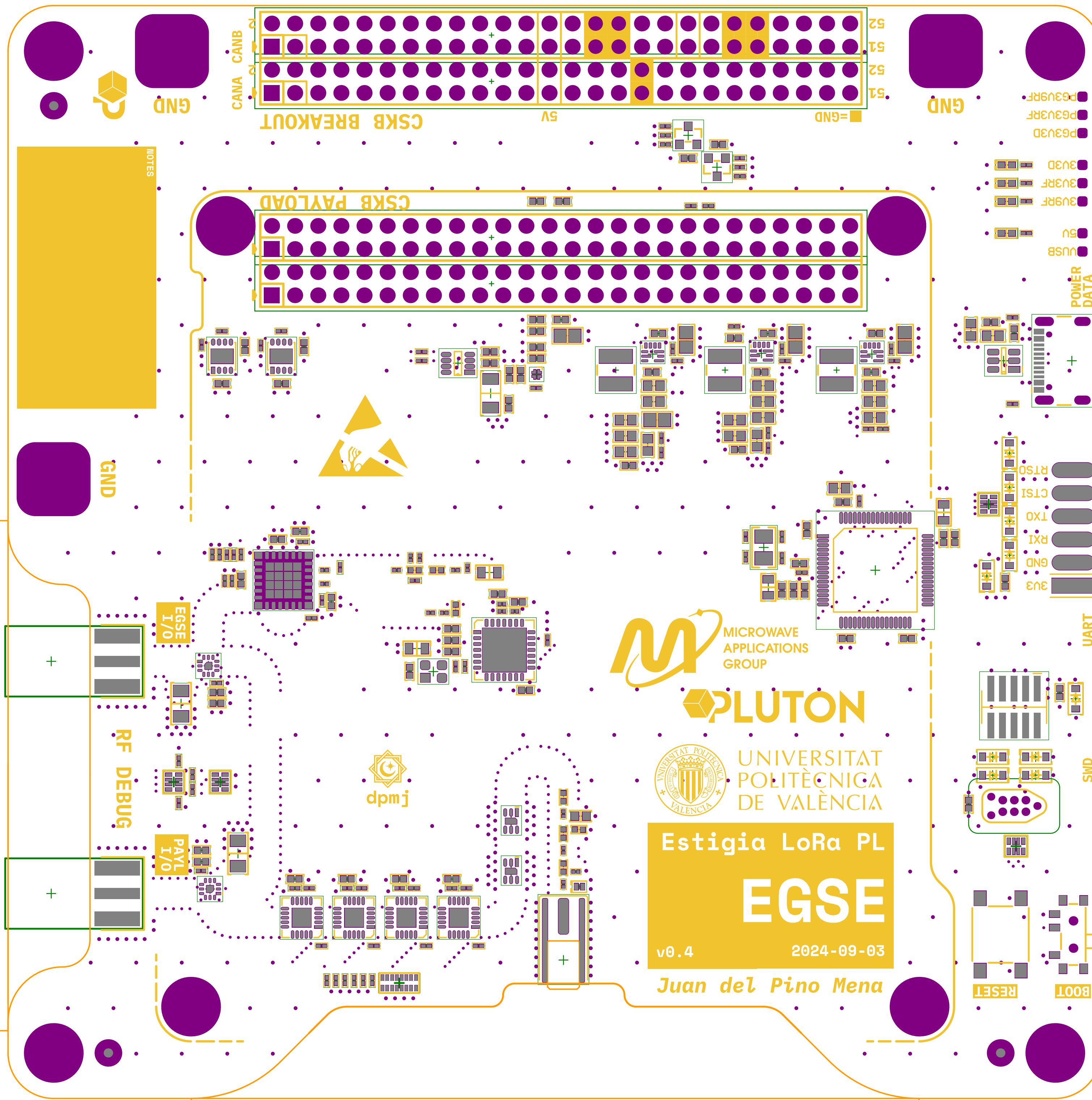
Pluton UPV	
Project: Estigia LoRa Comms PL - mPCIe SoM	
Layer: <span style="color: orange;">Board Shape</span> <span style="color: green;">Component Guard</span> <span style="color: purple;">Component Guard Dimension</span>	
Engineer: Juan Del Pino Mena	
Date: 2024-09-03	Revision: 0.3
	Size: A4



Layer	Name	Material	Thickness	Constant	Board Layer Stack
	Top Overlay				
	Top Solder	SM-001	0.025mm	4	
1	Top Layer	CF-004	0.018mm		
	Dielectric-1	PP-006	0.220mm	4.1	
2	GND-1	CF-004	0.035mm		
	Core-1	Core-035	0.350mm	4.7	
3	INT-SIG-1	CF-004	0.035mm		
	Dielectric-2	PP-006	0.220mm	4.1	
4	INT-SIG-2	CF-004	0.035mm		
	Core-2	Core-035	0.350mm	4.7	
5	GND-2	CF-004	0.035mm		
	Dielectric-3	PP-006	0.220mm	4.1	
6	Bottom Layer	CF-004	0.018mm		
	Bottom Solder	SM-001	0.025mm	4	
	Bottom Overlay				

Total board thickness: 1.586mm

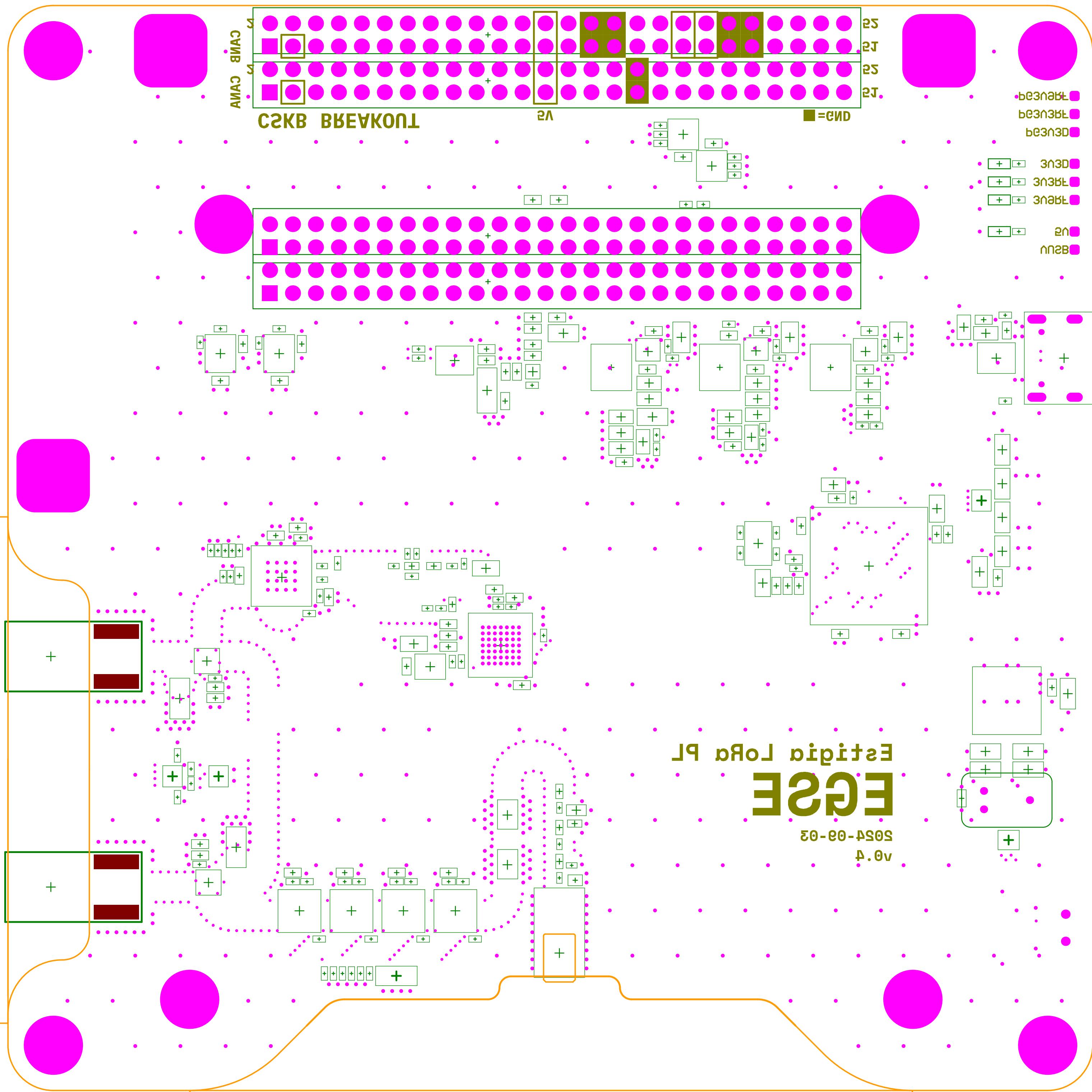
Pluton UPV	
Project: Estigia LoRa Comms PL - mPCIe SoM	
Layer: <span style="color: orange;">Board Shape</span> <span style="color: green;">Component Guard</span>	<span style="color: green;">Component Guard</span> <span style="color: purple;">Dimension</span>
Engineer: Juan Del Pino Mena	
Date: 2024-09-03	Revision: 0.3
	Size: A4



Layer	Name	Material	Thickness	Constant	Board Layer Stack
	Top Overlay				
	Top Solder	SM-001	0.025mm	4	
1	Top Layer	CF-004	0.018mm		
	Dielectric-1	PP-006	0.220mm	4.1	
2	GND-1	CF-004	0.035mm		
	Core-1	Core-035	0.350mm	4.7	
3	INT-SIG-1	CF-004	0.035mm		
	Dielectric-2	PP-006	0.220mm	4.1	
4	INT-SIG-2	CF-004	0.035mm		
	Core-2	Core-035	0.350mm	4.7	
5	GND-2	CF-004	0.035mm		
	Dielectric-3	PP-006	0.220mm	4.1	
6	Bottom Layer	CF-004	0.018mm		
	Bottom Solder	SM-001	0.025mm	4	
	Bottom Overlay				

Total board thickness: 1.586mm

Pluton UPV	
Project: Estigia LoRa Comms PL - mPCIe SoM	
Layer: Component Guard	
Board Shape: Component Guard	Component Guard
Component Guard	Top Dimension
Engineer: Juan Del Pino Mena	
Date: 2024-09-03	Revision: 0.3
Size: A4	



Layer	Name	Material	Thickness	Constant	Board Layer Stack
	Top Overlay				
	Top Solder	SM-001	0.025mm	4	
1	Top Layer	CF-004	0.018mm		
	Dielectric-1	PP-006	0.220mm	4.1	
2	GND-1	CF-004	0.035mm		
	Core-1	Core-035	0.350mm	4.7	
3	INT-SIG-1	CF-004	0.035mm		
	Dielectric-2	PP-006	0.220mm	4.1	
4	INT-SIG-2	CF-004	0.035mm		
	Core-2	Core-035	0.350mm	4.7	
5	GND-2	CF-004	0.035mm		
	Dielectric-3	PP-006	0.220mm	4.1	
6	Bottom Layer	CF-004	0.018mm		
	Bottom Solder	SM-001	0.025mm	4	
	Bottom Overlay				

Total board thickness: 1.586mm

Pluton UPV	
Project: Estigia LoRa Comms PL - mPCIe SoM	
Layer: Bottom Paste Guard	Board Shape, Bottom Component Guard
Engineer: Juan Del Pino Mena	Bottom Paste Guard, Bottom Solder Dimension
Date: 2024-09-03	Revision: 0.3
	Size: A4

